



## Structural Health Monitoring and NDE Methodologies for Smart Materials and Structures

Guest Editor:

**Dr. Evangelos Z. Kordatos**

Department of Engineering and  
Mathematics, Sheffield Hallam  
University, Sheffield S1 1WB, UK

Deadline for manuscript  
submissions:

**closed (31 December 2021)**

### Message from the Guest Editor

This Special Issue of *Applied Sciences* focuses on new developments and advances of SHM strategies and NDE methodologies for SMART materials and structures. The aim of this issue is to attract research involving novel and advanced methodologies or/and new applications that have an impact on the scientific community.

Potential topics include but are not limited to NDE for damage assessment, defect detection, property evaluation and fracture monitoring based on various non-destructive approaches, SHM systems for SMART materials and structures, sensor technologies for SHM and NDE, sensor integration and networks, smart systems for evaluation and monitoring, nanotechnology applied to SHM, integration of multiple NDE methodologies for enhanced monitoring, and interdisciplinary approaches for NDE and SHM.

- Non-destructive testing and evaluation (NDT/NDE)
- Structural health monitoring (SHM)
- SMART materials and structures
- Sensors for SHM and NDT/NDE
- Artificial intelligence for SHM and NDE
- Data fusion and feature extraction
- NDE integration





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## Editor-in-Chief

**Prof. Dr. Giulio Nicola Cerullo**

Dipartimento di Fisica,  
Politecnico di Milano, Piazza L.  
da Vinci 32, 20133 Milano, Italy

## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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*Applied Sciences* Editorial Office  
MDPI, St. Alban-Anlage 66  
4052 Basel, Switzerland

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